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ABSTRACT



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WAFER SURFACE TREATMENT APPARATUS

5 A wafer surface treatment apparatus with a waste liquid recovery
mechanism is used for treating a surface of a wafer with each of a treatment
liquid and a cleaning liquid. It comprises a wafer rotary holding apparatus
holding a to-be-treated wafer while rotating; and a waste liquid recovery
mechanism provided around the periphery of the wafer rotary holding apparatus
10 in a vertically movable manner. The waste liquid recovery mechanism is
constructed of a plurality of annular waste liquid recovery troughs which are
vertically movable relative to each other or one another and the annular waste
liquid recovery troughs are selectively used according to kinds of the treatment
liquid and the cleaning liquid, such that the respective waste liquids are
15 separately recovered.

(Fig. 5)